

S29WS256P

CS 81004

Qualification of: S29WS256P, 90nm MirrorBit®™ Flash Memory - 256 Mb (16 M x 16 bit), 1.8 V Burst Simultaneous Read/Write MirrorBit® Flash Memory in VBH084 (11.6 x 8.0 x 1.0mm) 84 Ball, Very Thin Fine Pitch Ball Grid Array Package (FBGA)



Reliability Qualification Summary

CONFIDENTIAL

NOTICE: The material in this report is confidential. It is prepared to assist in the qualification of our product. It is declassified for the internal use of our customers only, and may be modified to meet the needs of specific customers. It also serves as a record of full qualification according to JESD47 and AEC-Q100 Grade 1 requirements.

Additionally, the package details (material set, assembly location, etc.) are specific to the qual vehicle used for the qualification. Alternate material sets and assembly locations may be qualified for the product. Production material can be assembled with any qualified material set and at any qualified assembly location. Tests are performed in accordance with AEC-Q100 and relevant JEDEC specifications.

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I. Product Information

Product Description: S29WS256P
 90nm MirrorBit™ Flash Memory - 256 Mb (16 M x 16 bit),
 1.8 V Burst Simultaneous Read/Write MirrorBit® Flash Memory

Package:	VBH084	Qualification:	81004
Description:	(11.6 x 8.0 x 1.0mm) 84 Ball, Very Thin Fine Pitch Ball Grid Array Package (FBGA)		
Theta Ja:	39 °C/W	Psi Jt:	11 °C/W
Assembly Location:	Spansion Thailand	Molding Compound:	RoHS Compliant Epoxy Resin
Substrate/Leadframe:	BT Resin Substrate	Die Attachment:	Paste
Lead Finish:	96.5Sn3.0Ag0.5Cu Spheres	Bond Wire:	Gold
Comments:			

Est. Field Temperature:	55 °C	Life Test Temperature:	150 °C
Est. DC Field Current:	40 mA	Life Test Dynamic Current:	8 mA
Est. Field Voltage:	1.8 V	Life Test Voltage:	1.95 V
Est. Field Power Dissipation:	72 mWatts	Est. Stress Power Dissipation:	15.6 mWatts
Est. Field Tj:	57.8 °C	Est. Stress Tj:	150.6 °C

Die:	98456A	Die Size:	5.24 x 6.43 mm
Process:	CS129AL (90nm)	Fab:	Spansion Fab25
Type:	MirrorBit	Density:	256M

II. CS129/AL Life Test Failure Rate Calculation

HTOL Stress Temperature - 150 °C

Failure Mechanism	Read Points / Test Results				Modeling Parameters @ 55°C					Avg. Failure Rate FITS @ 55°C, 60% Conf.	
	24 hrs	168 hrs	504 hrs	1000 hrs	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life	Inherent Life
PLASTIC											
Sample Size	7640	7876	960	164							
Zero fails, Process ave. Ea	0 *	0	0	0	0.66	145	1	145		29	3
Totals	0	0	0	0					38052	29	3

* Contributes to early life FITS

Data Retention Bake - 150 °C

Reliability Stress	Number of Rejects	Sample Size	Failure Rate %	Failure Mechanism
500 hrs	0	2310	0.00	No Failures
1000 hrs	0	2171	0.00	No Failures
2000 hrs	0	1402	0.00	No Failures

III. Summary of Stress Test Results

Stress Test	Stress Condition	Package Type	Sample Size	Num. of Lots	Num. of Fails	Failure Rate %	Comments
Data From Qualification 81004:							
HTOL (EL)	(1.95V, 150°C)	VBH084 ¹	77	1	0	0.00	48 hours
	(1.95V, 150°C)	VBH084 ¹	77	1	0	0.00	168 hours
ESD CDM	N/A	VBH084 ¹	15	1	Passed 1.0kV		
ESD HBM	(100pF, 1500 Ohms)	VBH084 ¹	84	1	Passed 2.0kV		
Latch Up	(125°C, +/- 100mA)	VBH084 ¹	6	1	Passed		
Endurance (10k)	(-25°C, 1.7V)	VBH084 ¹	64	1	0	0.00	10k cycles
	(-25°C, 1.95V)	VBH084 ¹	64	1	0	0.00	10k cycles
	(90°C, 1.7V)	VBH084 ¹	64	1	0	0.00	10k cycles
	(90°C, 1.95V)	VBH084 ¹	64	1	0	0.00	10k cycles
Preconditioning	(PC1/260°C, +0°C/-5°C)	VBH084 ¹	77	1	Passed Jedec L3 / Jeita Rank E		
Generic Reference Data:							
Preconditioning	(PC1/260°C, +0°C/-5°C)	VBH084 ²	223	1	Passed Jedec L3 / Jeita Rank E		
Precon+Temp Cycle	(PC1/260°C, -40°C/150°C)	VBH084 ²	73	1	0	0.00	500 cycles
Precon+HAST	(PC1/260°C, Biased, 110°C/85% RH)	VBH084 ²	73	1	0	0.00	96 hours
Precon+Steam Pressure	(PC1/260°C, 121°C/100%RH/15PSIG)	VBH084 ²	77	1	0	0.00	168 hours

Notes / Justification: 1) Results from Qual 81004, S29WS256P, 256M CS129AL (90nm) MirrorBit in 84 Ball vFBGA (11.6 x 8 x 1mm)
 2) Results from Qual 80853, S29WS512P in 84 Ball vFBGA (11.6 x 8 x 1mm) - Same Package and Same Technology

Preconditioning Flows: PC1 (Exceeds JEDEC L3 and JEITA Rank E): Bake 125°C, 24hr => Soak @ 30°C/70%RH, 216hr => 3x Reflow

IV. Revision History

Section	Description
Revision A - 11/25/2010	Initial Release.

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